

What is claimed is:

1. A method for bonding an adherent member to a printed circuit board

comprising the steps of:

5 providing the printed circuit board having a substrate and a plurality of a first
conductive pattern group formed at a peripheral portion of the substrate in the direction
of the length of the substrate wherein the first conductive pattern group is adjusted
according to a thermal expansion degree of the substrate where the first conductive
pattern group is positioned;

10 providing the adherent member having a plurality of a second conductive pattern
group corresponding to the first conductive pattern group;

aligning the adherent member and the printed circuit board each other; and

bonding the adherent member to the printed circuit board by a thermo-
compression bonding method.

2. The method of claim 1, wherein the adjusted amount of the first
conductive pattern group has the largest value at both ends of the substrate and the
adjusted amount of the first conductive pattern group decreases toward a point dividing
the substrate into two portions.

3. The method of claim 1, wherein a thermal reaction property of a first half
portion of the substrate is different from a thermal reaction property of a second half
portion of the substrate when the substrate is divided lengthwise.

4. The method of claim 3, wherein an adjusted amount of the first conductive
pattern group positioned at the first portion of the substrate is larger toward the point
than an adjust amount of the first conductive pattern group positioned at the second
portion of the substrate wherein the thermal reaction property of the first portion of the

substrate is larger than the thermal reaction property of the second portion of the substrate.

5 5. The method of claim 3, wherein intervals among the first conductive pattern group positioned at the first portion of the substrate is larger than intervals among the first conductive pattern group positioned at the second portion of the substrate wherein the thermal reaction property of the first portion of the substrate is larger than the thermal reaction property of the second portion of the substrate.

10 6. The method of claim 1, wherein the thermo-compression bonding is performed through interposing an anisotropic conductive film between the printed circuit board and the adherent member.

7. The method of claim 1, wherein the second conductive pattern group has

intervals aligned with the first conductive pattern group before the first conductive pattern group is adjusted.

8. The method of claim 1, wherein the thermo-compression bonding is performed at a temperature of about 140 to 200 °C.

9. The method of claim 1, wherein the printed circuit board is connected to a thin film transistor substrate of a liquid crystal display device.

10. The method of claim 1, wherein the adherent member is a tape carrier package.

11. A liquid crystal display device, comprising:

a liquid crystal display panel having a thin film transistor substrate and a color

filter substrate attached to the thin film transistor substrate by interposing a liquid crystal between the color filter substrate and the thin film transistor substrate;

a printed circuit board electrically connected to the liquid crystal display panel;

and

an adherent member electrically connecting the liquid crystal display panel to the printed circuit board to operate the liquid crystal display panel, the adherent member attached to the printed circuit board by a thermo-compression bonding method,

wherein a misalignment amount of a conductive pattern group of an output of the printed circuit board is identical to a misalignment amount of a conductive pattern group of an input of the adherent member.

12. The liquid crystal display device as claimed in claim 11, wherein a thermal reaction property of one half portion of the printed circuit board is different from a thermal reaction property of the other half portion of the printed circuit board when

dividing the printed circuit board lengthwise.